Package Outline Drawing

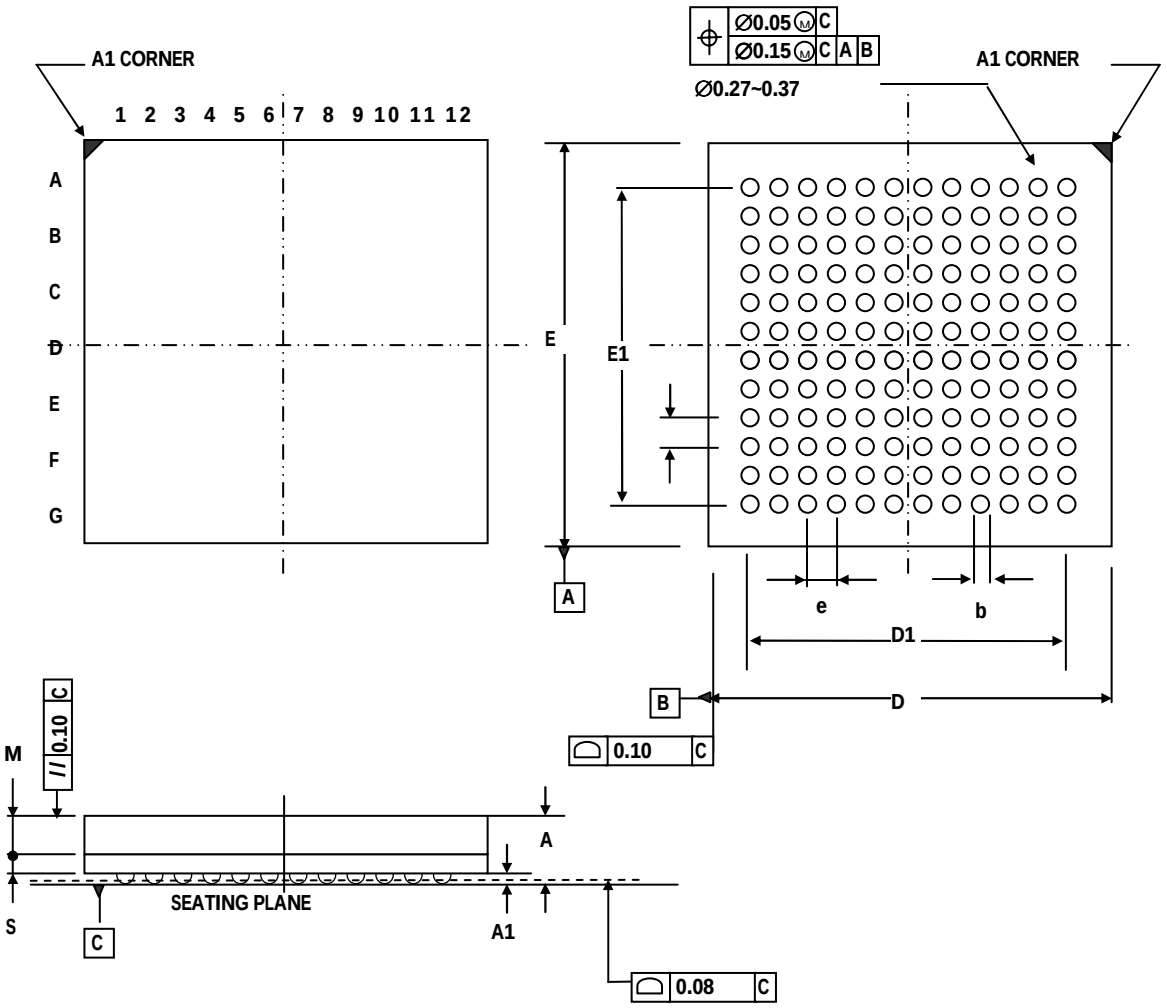
V144.7X7A

144 Lead Thin, Fine Pitch Plastic ball Grid Array Package (TFBGA)

Rev 0, 1/11

TOP VIEW

BOTTOM VIEW



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Symbol	Millimeter		
	Min.	Nom.	Max.
A	---	---	1.20
A1	0.16	---	0.26
M	0.53 Ref.		
S	0.26 Ref.		
b	0.27	0.30	0.37
e	0.50 Basic		
D	6.90	7.00	7.10
D1	---	5.50	---
E	6.90	7.00	7.10
E1	---	5.50	---

Note:

1. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.

2. Dimension b is measured at the maximum solder ball diameter, parallel to primary datum C.

3. Controlling dimension : Millimeter.

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